SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR) SDLS074 – DECEMBER 1972 – REVISED MARCH 1988

- Cascading Circuitry Provided Internally
- Synchronous Operation
- Individual Preset to Each Flip-Flop
- Fully Independent Clear Input

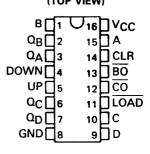
TYPES	TYPICAL MAXIMUM	TYPICAL
	COUNT FREQUENCY	POWER DISSIPATION
'192,'19 3	32 MHz	325 mW
'LS192,'LS193	32 MHz	95 mW

description

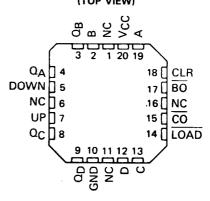
These monolithic circuits are synchronous reversible (up/down) counters having a complexity of 55 equivalent gates. The '192 and 'LS192 circuits are BCD counters and the '193 and 'LS193 are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidently with each other when so instructed by the steering logic. This mode of operation eliminates the output counting spikes which are normally associated with asynchronous (rippleclock) counters.

The outputs of the four master-slave flip-flops are triggered by a low-to-high-level transition of either count (clock) input. The direction of counting is determined by which count input is pulsed while the other count input is high.

All four counters are fully programmable; that is, each output may be preset to either level by entering the desired data at the data inputs while the load input is low. The output will change to agree with the data inputs independently of the count pulses. This feature SN54192, SN54193, SN54LS192, SN54LS193...J OR W PACKAGE SN74192, SN74193...N PACKAGE SN74LS192, SN74LS193...D OR N PACKAGE (TOP VIEW)



SN54LS192, SN54LS193 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

allows the counters to be used as modulo-N dividers by simply modifying the count length with the preset inputs.

A clear input has been provided which forces all outputs to the low level when a high level is applied. The clear function is independent of the count and load inputs. The clear, count, and load inputs are buffered to lower the drive requirements. This reduces the number of clock drivers, etc., required for long words.

These counters were designed to be cascaded without the need for external circuitry. Both borrow and carry outputs are available to cascade both the up- and down-counting functions. The borrow output produces a pulse equal in width to the count-down input when the counter underflows. Similarly, the carry output produces a pulse equal in width to the count-up input when an overflow condition exists. The counters can then be easily cascaded by feeding the borrow and carry outputs to the count-down and count-up inputs respectively of the succeeding counter.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	SN54'	SN54LS'	SN74'	SN74LS'	UNIT
Supply voltage, V _{CC} (see Note 1)	7	7	7	7	V
Input voltage	5.5	7	5.5	7	V
Operating free-air temperature range	- 55	to 125	0	to 70	°C
Storage temperature range	- 65	to 150	-65	to 150	°C

NOTE 1: Voltage values are with respect to network ground terminal.

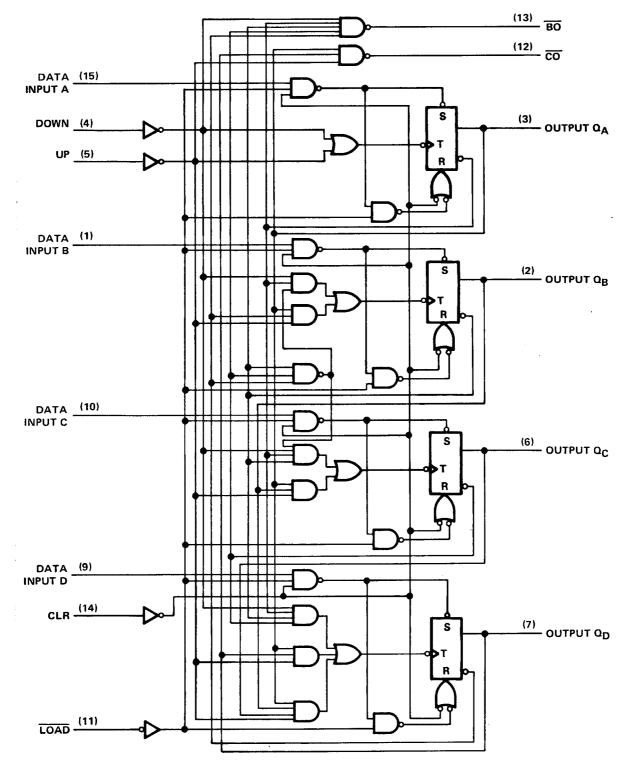
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54192, SN54LS192, SN74192, SN74LS192 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 – DECEMBER 1972 – REVISED MARCH 1988

logic diagram (positive logic)



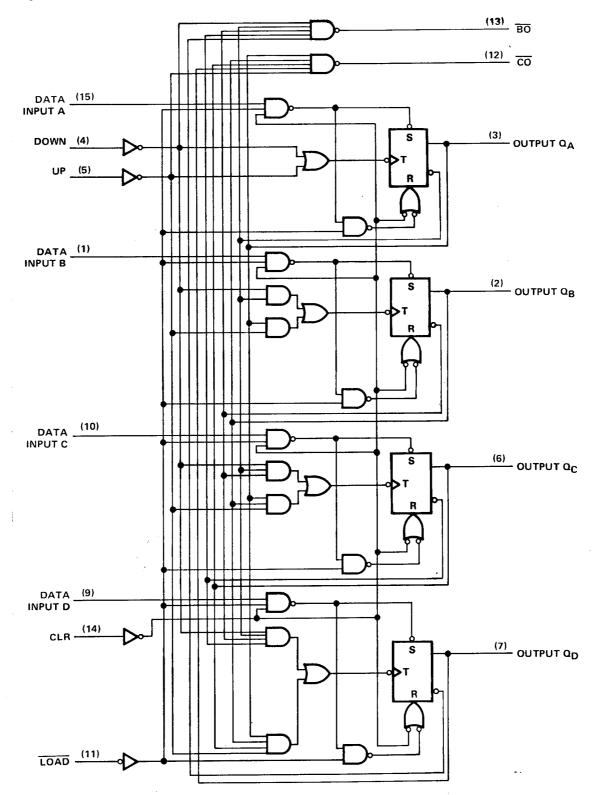
Pin numbers shown are for D, J, N, and W packages.



SN54193, SN54LS193, SN74193, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 - DECEMBER 1972 - REVISED MARCH 1988

logic diagram (positive logic)



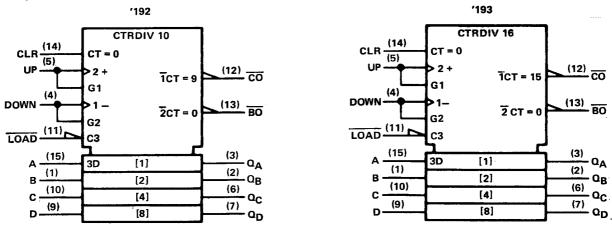
Pin numbers shown are for D, J, N, and W packages.



SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 - DECEMBER 1972 - REVISED MARCH 1988

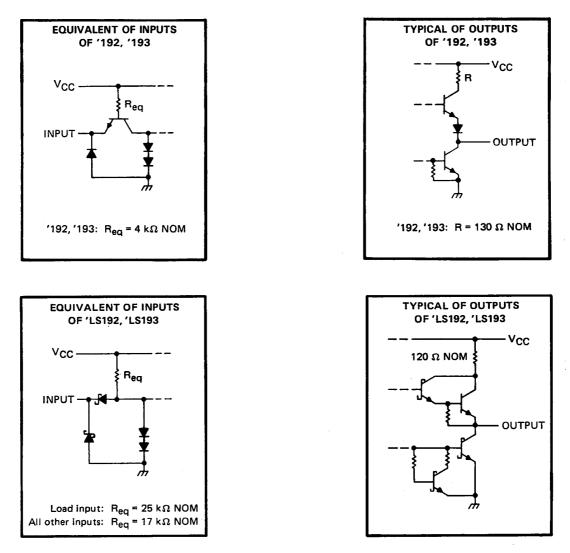
logic symbols[†]



 $^{\dagger} \text{These}$ symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs





SN54192, SN54LS192, SN74192, SN74LS192 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

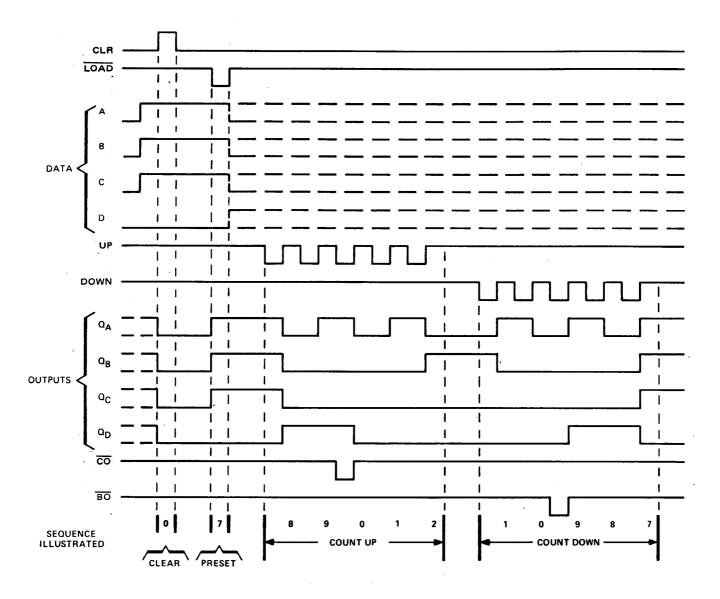
SDLS074 – DECEMBER 1972 – REVISED MARCH 1988

'192, 'LS192 DECADE COUNTERS

typical clear, load, and count sequences

Illustrated below is the following sequence:

- 1. Clear outputs to zero.
- 2. Load (preset) to BCD seven.
- 3. Count up to eight, nine, carry, zero, one, and two.
- 4. Count down to one, zero, borrow, nine, eight, and seven.



NOTES: A. Clear overrides load, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.



SN54193, SN54LS193, SN74193, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

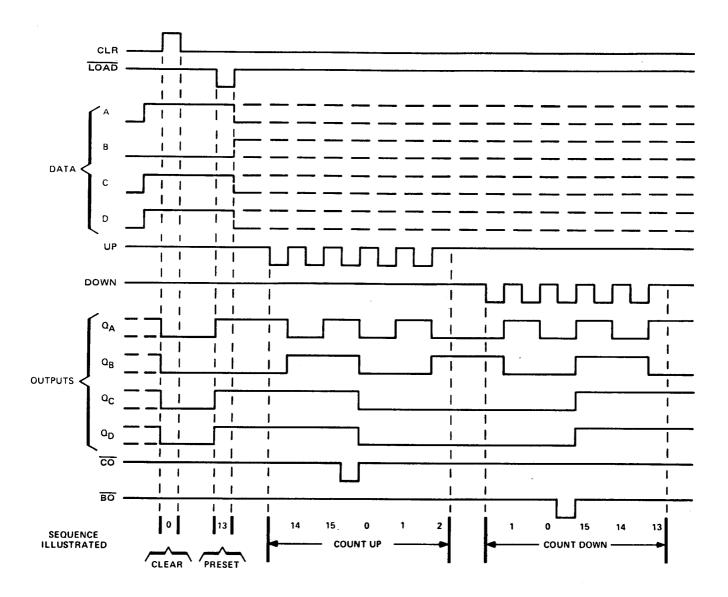
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'193, 'LS193 BINARY COUNTERS

typical clear, load, and count sequences

Illustrated below is the following sequence:

- 1. Clear outputs to zero.
- 2. Load (preset) to binary thirteen.
- 3. Count up to fourteen, fifteen, carry, zero, one, and two.
- 4. Count down to one, zero, borrow, fifteen, fourteen, and thirteen.



NOTES: A. Clear overrides load, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.



SN54192, SN54193, SN74192, SN74193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 - DECEMBER 1972 - REVISED MARCH 1988

recommended operating conditions

				SN5419 SN5419			SN7419 SN7419		
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
юн	High-level output current				-0.4			-0.4	mA
IOL .	Low-level output current			16			16	mA	
fclock	Clock frequency		0		25	0		25	MHz
tw	Width of any input pulse		20			20			ns
t _{su}	Data setup time, (see Figure 1)		20			20			ns
		Data, high or low	0	-		0			
th	Hold time	LOAD	3			3			ns
Т _А	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN5419	2		SN7419	2	
	PARAMETER	TEST CONDITIONS [†]		SN5419	3				
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage		2			2	•		V
VIL	Low-level input voltage				0.8			0.8	V
VIK	Input clamp voltage	$V_{CC} = MIN$, $I_I = -12 \text{ mA}$			-1.5			-1.5	V
∨он	High-level output voltage	$V_{CC} = MIN, V_{IH} = 2 V,$ $V_{IL} = 0.8 V, I_{OH} = -0.4 mA$	2.4	3.4		2.4	3.4		v
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V V _{IL} = 0.8 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	v
Ц	Input current at maximum input voltage	V _{CC} = MAX, V ₁ = 5.5 V			1			1	mA
ЧН	High-level input current	V _{CC} = MAX, V ₁ = 2.4 V	1		40			40	μA
1 ₁ L	Low-level input current	V _{CC} = MAX, V ₁ = 0.4 V			-1.6			-1.6	mA
los	Short-circuit output current§	V _{CC} = MAX	-20		-65	-18		-65	mA
1cc	Supply current	V _{CC} = MAX, See Note 2		65	89		65	102	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. [‡]All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $\S{}Not more than one output should be shorted at a time.$

NOTE 2: ICC is measured with all outputs open, clear and load inputs grounded, and all other inputs at 4.5 V.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER¶	FROM INPUT	TO OUTPUT	TEST CONDITIONS	MIN	түр	MAX	UNIT
f _{max}				25	32		MHz
^t PLH	LID.	co	7		17	26	
^t PHL	UP	CO			16	24	ns
^t PLH	DOWN	BO	С L = 15 рF,		16	24	
^t PHL	DOWN	во	$R_{L} = 400 \Omega,$		16	24	ns
^t PLH		Q	See Figures 1 and 2		25	38	
^t PHL	UP OR DOWN	ŭ			31	47	ns
tPLH		0	7		27	40	
^t PHL	LOAD	Q			29	40	ns
^t PHL	CLR		22	35	ns		

¶f_{max} ≡ maximum clock frequency

tpLH = propagation delay time, low-to-high-level output

 $t_{PHL} \equiv propagation delay time, high-to-low-level output$



SN54LS192, SN54LS193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 – DECEMBER 1972 – REVISED MARCH 1988

recommended operating conditions

		SI SI	-	92 93	UNIT			
		MIN	NOM	MAX	MIN	NOM	MAX	1
Vcc	Supply voltage	4.5	. 5	5.5	4.75	5	5.25	V
юн	High-level output current			-400			-400	μA
IOL	Low-level output current			4			8	mA
fclock	Clock frequency	0		25	0		25	MHz
tw	Width of any input pulse	20			20		•	ns
	Clear inactive-state setup time	15			15			ns
t _{su}	Load inactive-state setup time	15			15			ns
	Data setup time (see Figure 1)	20			20			ns
th	Data hold time	5			5			ns
TA	Operating free-air temperature range	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

I

	PARAMETER	TE	ST CONDITIONS	;†	4 ·	N54LS1 N54LS1		I Ş S	UNIŢ		
			•.		MIN	түр‡	MAX	MIN	түр‡	MAX	
VIH	High-level input voltage				2			2			v
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I =18 mA				-1.5			-1.5	v
∨он	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V, , 1 _{OH} = -400 μA	· · · · · · · · · · · · · · · · · · ·	2.5	3.4		2.7	3.4		v
VOL	Low-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V,	$I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$		0.25	0.4		0.15 0.35	0.4 0.5	v
lj –	Input current at maximum input voltage	V _{CC} = MAX,	V; = 7 V				0.1			0.1	∶mA
ŧн	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μA
hε	Low-level input current	V _{CC} = MAX,	VI = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current§	V _{CC} = MAX			20		-100	-20		-100	mA
Icc	Supply current	V _{CC} = MAX,	See Note 2			19	34		19	- 34	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. [‡]All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

\$Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open, clear and load inputs grounded, and all other inputs at 4.5 V.

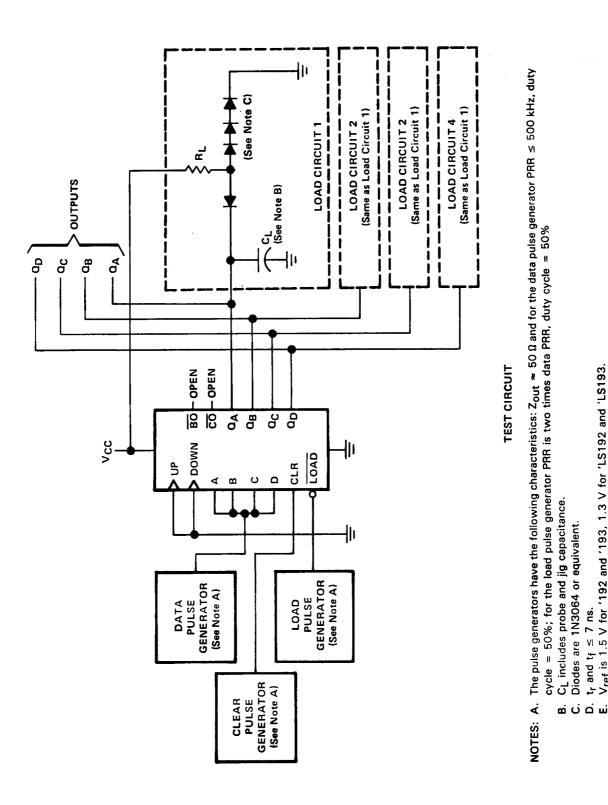
switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM INPUT	το ουτρυτ	TEST CONDITIONS	MIN	түр	MAX	UNIT	
f _{max}				25	32		MHz	
tPLH	LID	<u>co</u>	7		17	26		
tPHL	- UP	0			18	24	ns	
^t PLH	DOWN	BO	C _L = 15 pF, R _L = 2 kΩ,		16	24		
tPHL	DOWN	во			15	24	ns	
^t PLH		0	See Figures 1 and 2		27	38		
tPHL	UP OR DOWN	Q			30	47	ns	
tPLH			-		24	40		
tPHL	LOAD	۵			25	40	ns	
tPHL	CLR	CLR Q						



SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR) SDLS074 – DECEMBER 1972 – REVISED MARCH 1988

PARAMETER MEASUREMENT INFORMATION

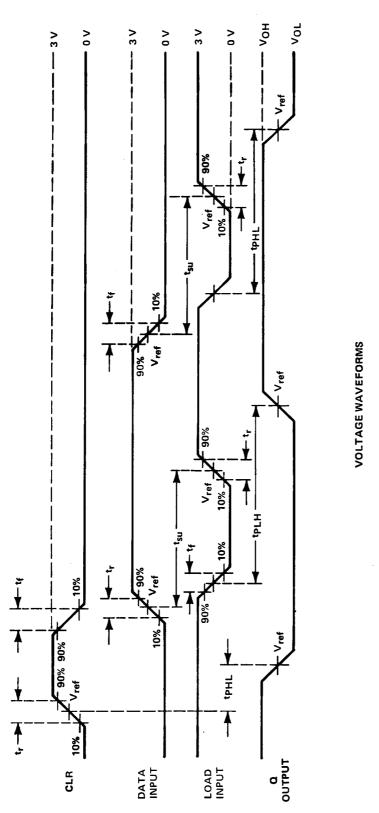


Texas INSTRUMENTS POST OFFICE BOX 655303 • DALLAS, TEXAS 75265 FIGURE 1A -- CLEAR, SETUP AND LOAD TIMES

 \dot{V}_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

 t_r and $t_f \leq 7$ ns.

PARAMETER MEASUREMENT INFORMATION



EXAS **ISTRUMENTS**

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NOTES: A. The pulse generators have the following characteristics: Z_{out} ≈ 50 Ω and for the data pulse generator PRR ≤ 500 kHz, duty cycle = 50%; for the load pulse generator PRR is two times data PRR, duty cycle = 50%

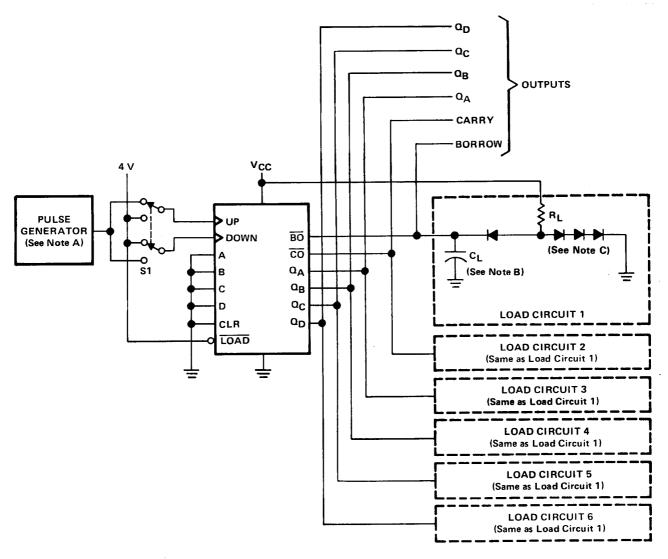
- CL includes probe and jig capacitance. ப்ப்ப்
 - Diodes are 1N3064 or equivalent.
 - t_{f} and $t_{f} \leq 7$ ns.
- V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 1B - CLEAR, SETUP, AND LOAD TIMES

SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 - DECEMBER 1972 - REVISED MARCH 1988

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

NOTES: A. The pulse generators have the following characteristics: PRR \approx 1 MHz, Z_{out} \approx 50 Ω , duty cycle = 50%.

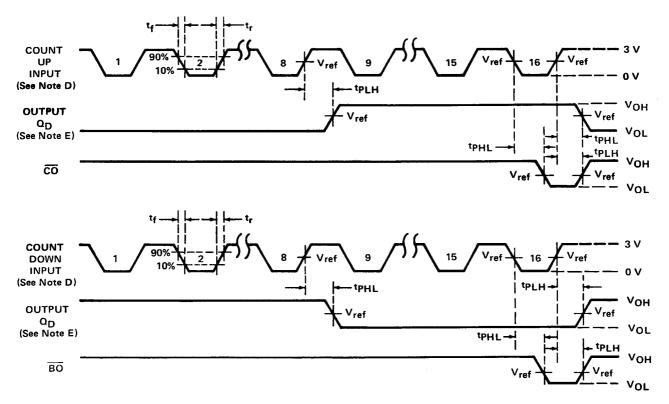
- B. CL includes probe and jig capacitance.
- C. Diodes are 1N3064 or equivalent.
- D. Cout-up and dount-down pulse shown are for the '193 and 'LS193 binary counters. Count cycle for '192 and 'LS192 decade counters is 1 through 10.
- E. Waveforms for outputs Q_A , Q_B , and Q_C are omitted to simplify the drawing.
- F. t_r and $t_f \leq 7$ ns.
- G. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 2A - PROPAGATION DELAY TIMES



SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR) SDLS074 - DECEMBER 1972 - REVISED MARCH 1988

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

- NOTES: A. The pulse generators have the following characteristics: PRR \approx 1 MHz, Z_{out} \approx 50 Ω , duty cycle = 50%.
 - B. CL includes probe and jig capacitance.
 - C. Diodes are 1N3064 or equivalent.
 - D. Cout-up and dount-down pulse shown are for the '193 and 'LS193 binary counters. Count cycle for '192 and 'LS192 decade counters is 1 through 10.
 - E. Waveforms for outputs Q_A , Q_B , and Q_C are omitted to simplify the drawing.
 - F. t_r and $t_f \leq 7$ ns.
 - G. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 2B - PROPAGATION DELAY TIMES





25-Oct-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-9558401QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QE A SNJ54192J	Samples
5962-9558401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A SNJ54192W	Samples
5962-9558401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A SNJ54192W	Samples
76006012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
76006012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
7600601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
7600601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
7600601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples
7600601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples
JM38510/01309BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/01309BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Samples
JM38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Samples
JM38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Samples
JM38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Samples
JM38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Samples





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Orderable Device	Status	Package Type	-	Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
JM38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Sample
JM38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Sample
JM38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Sampl
M38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Sampl
M38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Sampl
M38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Sampl
M38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Sampl
M38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Sampl
M38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Sampl
M38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Samp
M38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Samp
SN54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54192J	Samp
SN54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54192J	Samp
SN54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS193J	Samp
SN54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS193J	Samp
SN74192N	OBSOLETE	E PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74193N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74193N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sampl
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74193N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74193N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samp
SN74LS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samp
SN74LS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samp
SN74LS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samp
SN74LS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Samj
SN74LS193N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Samp
SN74LS193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Samj
SN74LS193NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Samj
SN74LS193NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Samj
SN74LS193NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sam
SNJ54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QE A	Sam
SNJ54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54192J 5962-9558401QE A	Sam



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Giy	(2)	(6)	(3)		(4/5) SNJ54192J	
SNJ54192W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A	Samples
										SNJ54192W	
SNJ54192W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A	Samples
										SNJ54192W	
SNJ54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54193W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54193W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS193FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
SNJ54LS193FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
SNJ54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
SNJ54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
SNJ54LS193W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples
SNJ54LS193W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.



PACKAGE OPTION ADDENDUM

25-Oct-2016

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54192, SN54193, SN54LS193, SN54LS193-SP, SN74192, SN74193, SN74LS193 :

• Catalog: SN74192, SN74193, SN74LS193, SN54LS193

- Military: SN54192, SN54193, SN54LS193
- Space: SN54LS193-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS

Texas Instruments





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nomina	I											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS193DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS193NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS193DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS193NSR	SO	NS	16	2000	367.0	367.0	38.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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